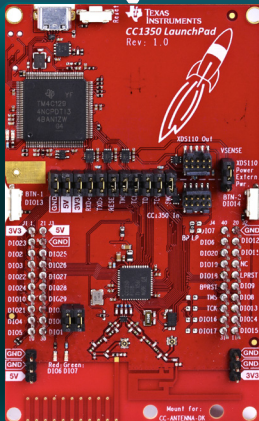




CC1350 LaunchPad™

// wireless microcontroller development kit for rapid prototyping.
LAUNCHXL-CC1350



LAUNCH
YOUR DESIGN

START @

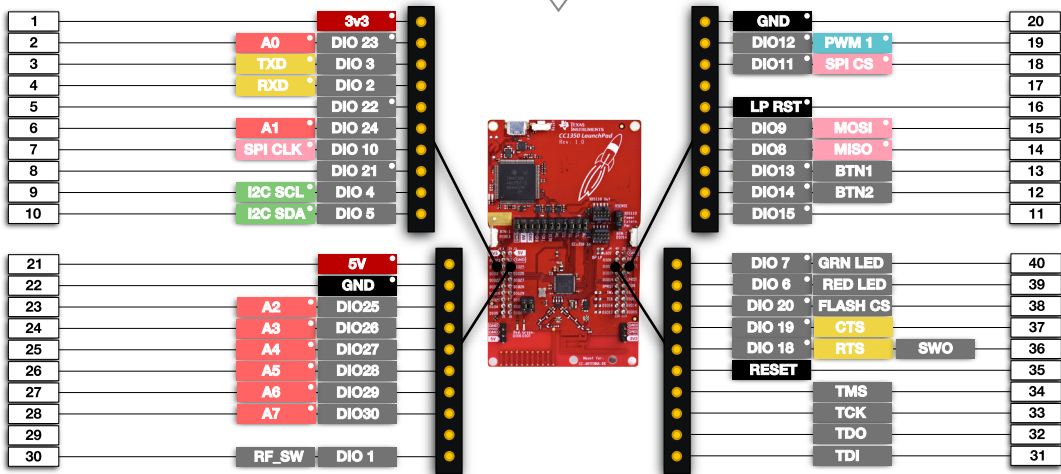
dev.ti.com/launchxl-cc1350



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○ Pin aligns with BoosterPack pinout standard.
 Make your own BoosterPack @ www.ti.com/byob



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